

## Item # Tflex HR200, Tflex HR200 Series Thermal Gap Filler



### Tflex HR200 Series Thermal Gap Filler

#### MID-PERFORMANCE GAP FILLER WITH 1.6 W/MK

Tflex™ HR200 is a cost-effective and compliant gap filler thermal interface material with excellent thermal performance and great handling for mass-production applications.

The low modulus interface pad conforms to component topography, resulting in little stress on the components, mating chassis or parts. The softness relieves mechanical stress from high stack-up tolerance and absorbs shock, resulting in improved device reliability.

Tflex™ HR200 is naturally tacky on both sides and requires no additional adhesive coating to inhibit thermal performance.

The tack is designed to hold the pad in place during assembly and component transport.

Tflex™ HR200 is stable from -50°C thru 160°C.

## SPECIFICATIONS

Construction and Composition	Naturally tacky Ceramic filled silicone elastomer
Color	Grey
Thermal Conductivity	1.6 W/m-K
Hardness (Shore 00)	50
Specific Gravity	2.4 g/cc
Available Thickness Range	0.020 - 0.320 inches
Temperature Range	-50 to 160 °C
Outgassing TML	0.35 %
Outgassing CVCM	0.06 %
Coefficient of Thermal Expansion	296.54 ppm/°C